

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: Unknown

Inventor: Chang, et al

Serial No. Filed Herewith

Filed: Filed Herewith

For: Method For Forming Electrically Conductive
Bumps and Devices Formed

Attorney Docket No.: 64,600-065

#2
11/1/00
M. PradginCERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: August 7, 2000

- DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.56

Assistant Commissioner
for Patents
Washington, D.C. 20231

Sir:

In compliance with 37 C.F.R. § 1.56, the art listed and identified on the attached Form PTO-1449 is being submitted herewith for consideration by the Examiner. A copy of each of the listed references is included herewith.

It is Applicant's opinion that the claims presently on file patentably distinguish the present invention from each of these references. The above references are being cited only in the interests of candor and without any admission that they constitute

U.S.S.N: Filed Herewith

statutory prior art or contain matter which anticipates the invention or which would render the same obvious, either singly or in combination, to a person of ordinary skill in the art.

The Commissioner is authorized to charge any fees which may be required to Deposit Account No. 50-0484.

Respectfully submitted,

TUNG & ASSOCIATES

By 

Randy W. Tung
Reg. No. 31,311
838 W. Long Lake Road
Suite 120
Bloomfield Hills, MI 48302
(248) 540-4040

Date: August 7, 2000